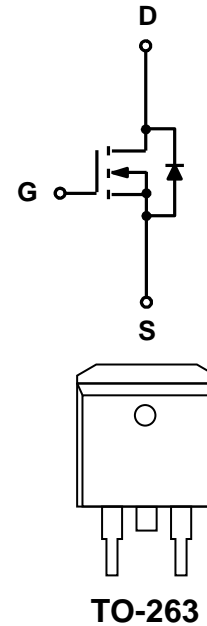


Features

- 150V,100A
 $R_{DS(ON)} < 6.0m\ \Omega @ V_{GS}=10V$ TYP:5.4 m Ω
 $R_{DS(ON)} < 7.0m\ \Omega @ V_{GS}=6V$ TYP:6.0m Ω
- Surface-mounted package
- Super Trench
- Advanced trench cell design

Applications

- LCD TV appliances
- LCDM appliances
- High power inverter system



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity (PCS)
G060N15D	APG060N15D	TO-263	-	-	800

ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	150	V
Gate-Source Voltage	V_{GS}	± 25	V
Continuous Drain Current ($T_C=25^\circ\text{C}$) ^(1,3)	I_D	100	A
Continuous Drain Current ($T_C=100^\circ\text{C}$) ^(1,3)	I_D	66	A
Pulsed Drain Current ^(1,2,3)	I_{DM}	180	A
Single Pulsed Avalanche Energy ($V_{DD}=50V, L=1.0mH$)	E_{AS}	1250	mJ
Drain Power Dissipation	P_D	156	W
Thermal Resistance from Junction to Case ⁽²⁾	$R_{\theta JC}$	0.8	$^\circ\text{C}/\text{W}$
Thermal Resistance- Junction to Ambient ⁽²⁾	$R_{\theta JA}$	40	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~ +150	$^\circ\text{C}$

Notes:

1. Pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\ \%$
2. Surface Mounted on minimum footprint pad area.
3. Limited by bonding wire

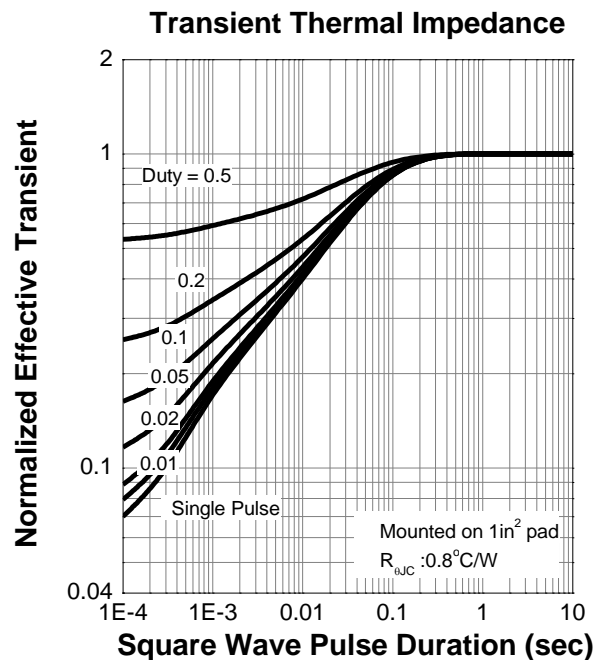
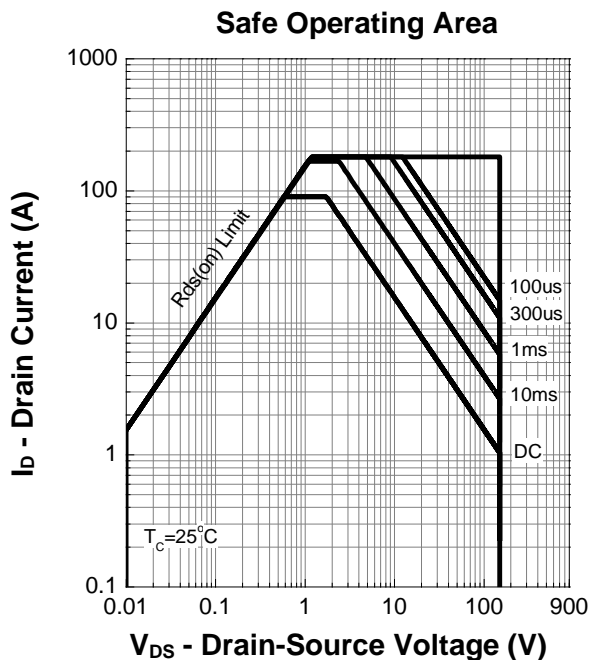
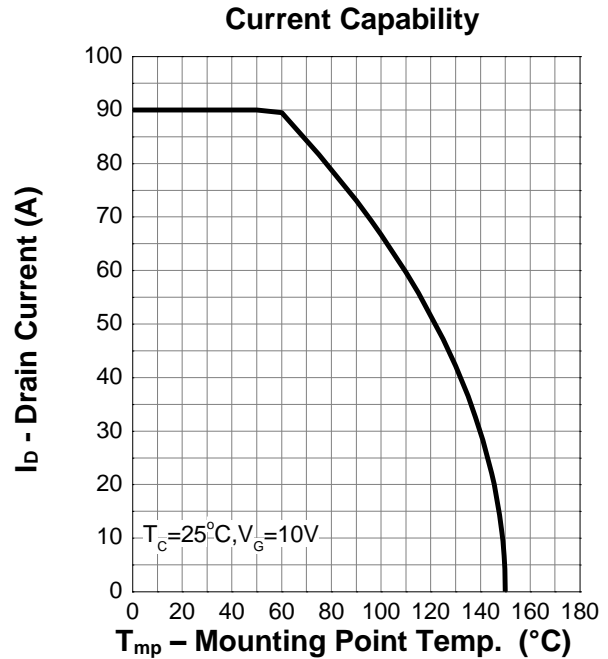
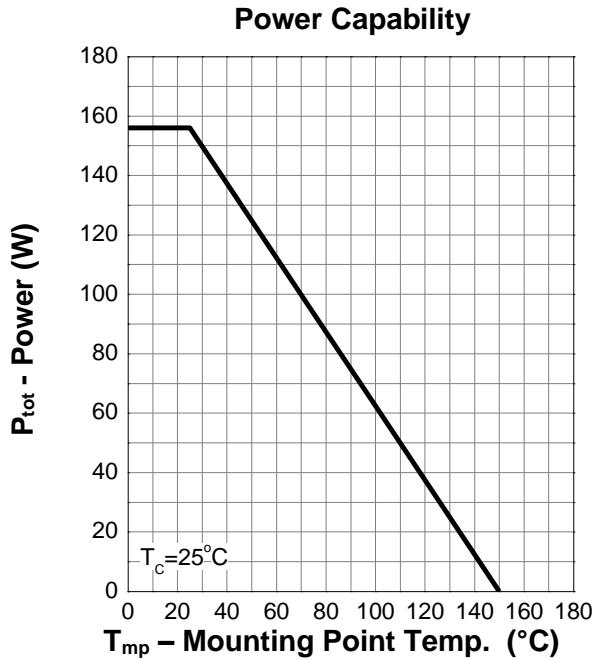
MOSFET ELECTRICAL CHARACTERISTICS(T_a=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =250μA	150	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =120V, V _{GS} = 0V	-	-	1	μA
Gate-body leakage current	I _{GSS}	V _{GS} = ±25V, V _{DS} = 0V	-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2.0	-	4.0	V
Drain-source on-resistance ^(a)	R _{DS(on)}	V _{GS} =10V, I _D =50A	-	5.4	6.0	mΩ
		V _{GS} =6V, I _D =30A	-	6.0	7.0	mΩ
Dynamic characteristics						
Input Capacitance	C _{iss}	V _{DS} =75V, V _{GS} =0V, f =1.0MHz	-	9019	-	pF
Output Capacitance	C _{oss}		-	583	-	
Reverse Transfer Capacitance	C _{rss}		-	63	-	
Switching characteristics						
Turn-on delay time	t _{d(on)}	V _{DD} =75V, I _D =50A, R _G =3.9Ω, V _G =10V	-	23	-	ns
Turn-on rise time	t _r		-	66	-	
Turn-off delay time	t _{d(off)}		-	89	-	
Turn-off fall time	t _f		-	70	-	
Total Gate Charge	Q _g	V _{DS} =75V, I _D =50A, V _{GS} =10V	-	131	-	nC
Gate-Source Charge	Q _{gs}		-	47	-	
Gate-Drain Charge	Q _{gd}		-	24	-	
Source-Drain Diode characteristics						
Diode Forward voltage ^(a)	V _{SD}	T _C =25°C, V _{GS} =0V, I _S =50A	-	-	1.3	V
Diode Forward current	I _S	T _C =25°C	-	-	104	A
Body Diode Reverse Recovery Time	t _{rr}	T _C =25°C, I _F =50A, di/dt=100A/us		112		ns
Body Diode Reverse Recovery Charge	Q _{rr}	T _C =25°C, I _F =50A, di/dt=100A/us		475		nc

Notes:

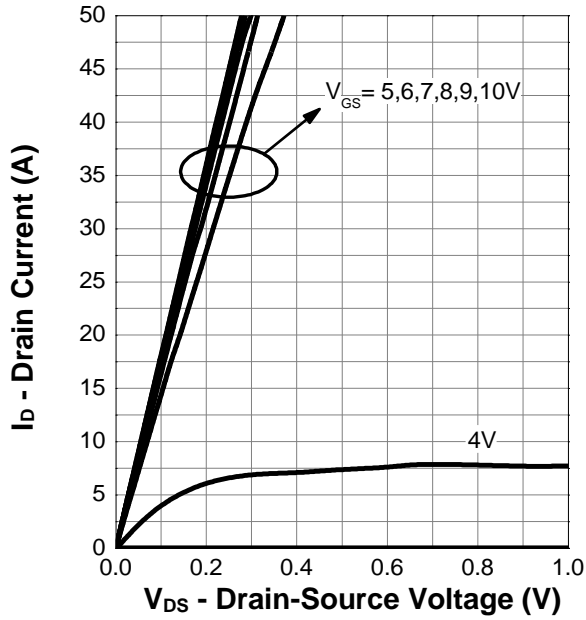
- a) : Pulse test ; pulse width ≤ 300 μs, duty cycle ≤ 2%
- b) : Guaranteed by design, not subject to production testing

Typical Characteristics

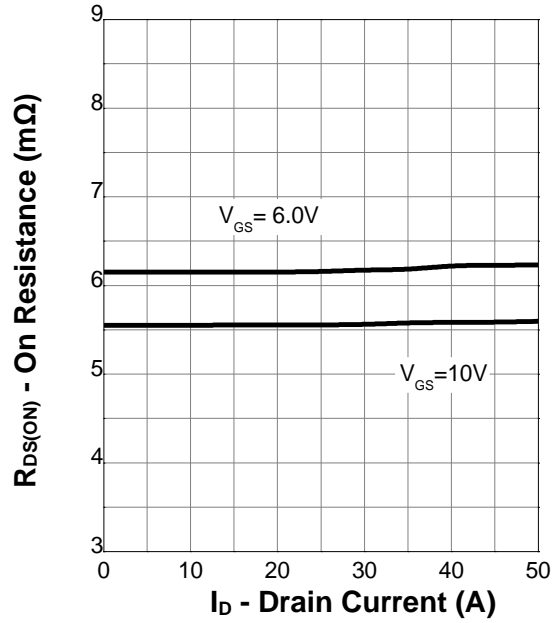


Typical Characteristics (cont.)

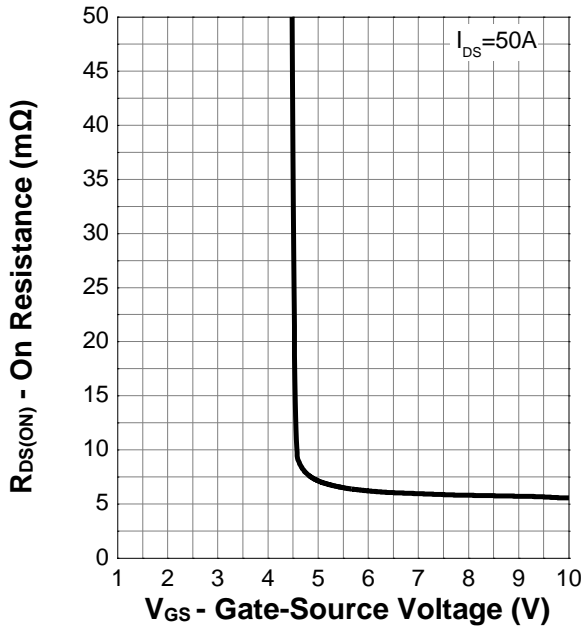
Output Characteristics



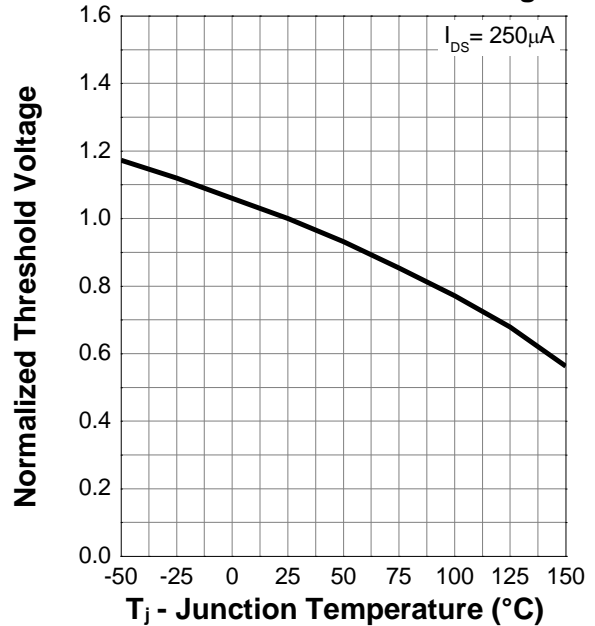
On Resistance



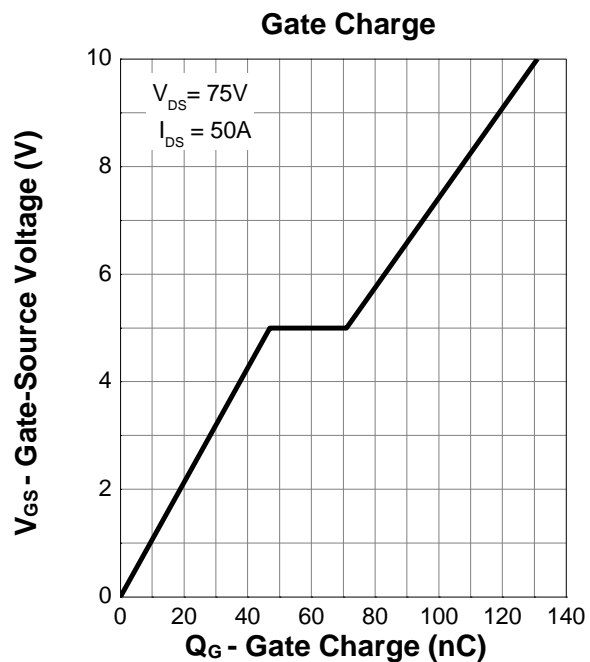
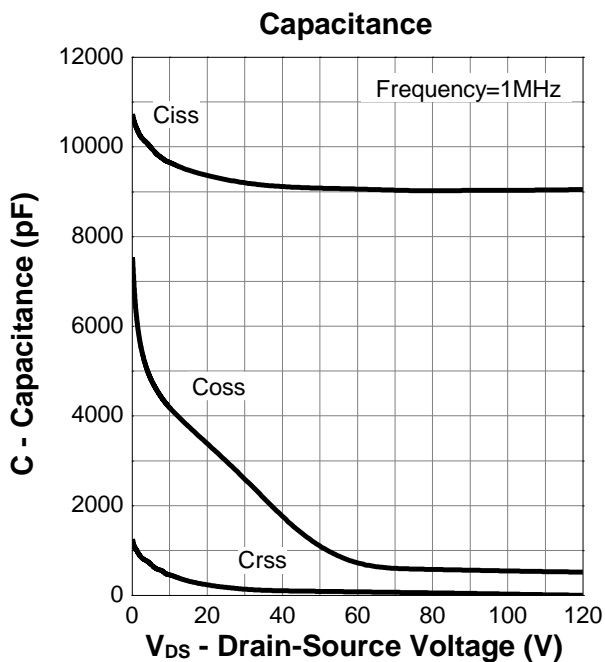
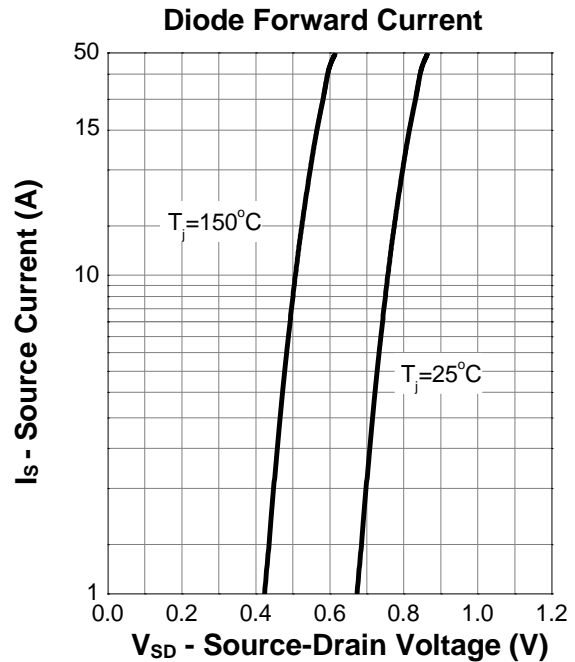
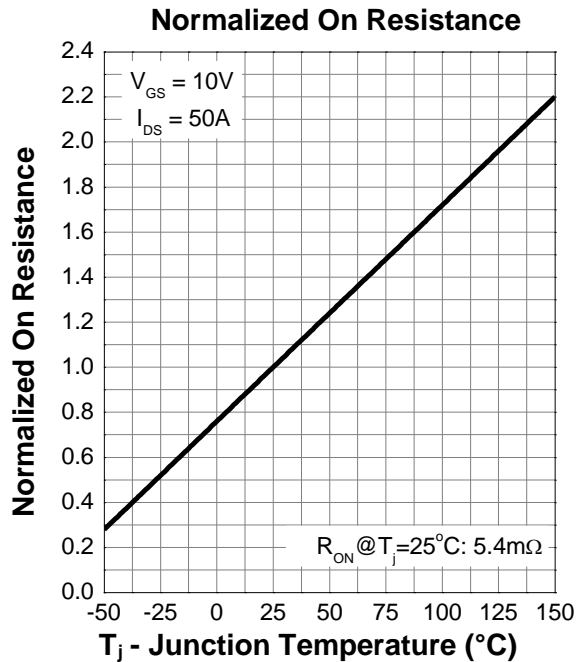
Transfer Characteristics



Normalized Threshold Voltage

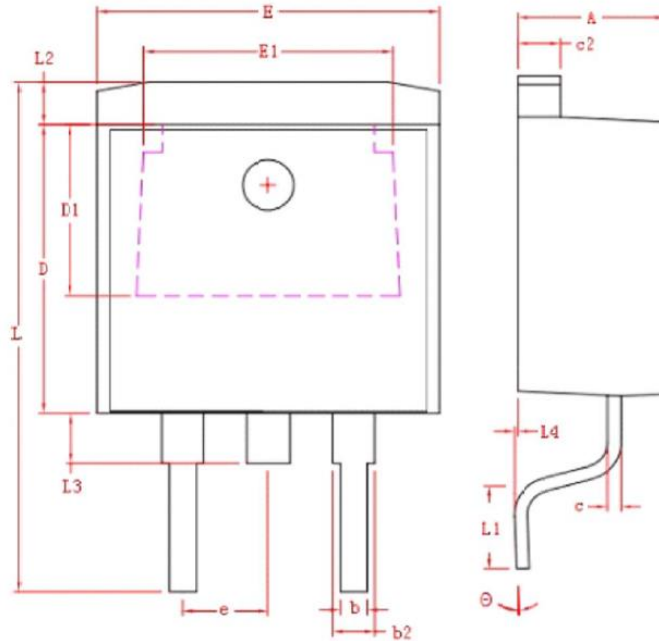


Typical Characteristics (cont.)



Package Dimensions

TO-263



Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	4.40	4.80
b	0.76	1.00
L4	0.00	0.25
C	0.36	0.50
L3	1.50 REF	
L1	2.29	2.79
E	9.80	10.40
E1	7.40 REF	
c2	1.25	1.45
b2	1.17	1.47
D	8.60	9.00
D1	5.10 REF	
e	2.54 REF	
L	14.6	15.8
θ	0° ± 3°	
L2	1.27 REF	